

SOT2142-1

VFBGA486, very thin, fine-pitch ball grid array package, 486 terminals, 0.5 mm pitch, 14 mm x 14 mm x 0.825 mm body

25 May 2021

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA486
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	04-05-2021
Manufacturer package code	98ASA01778D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	13.9	14	14.1	mm
package width	13.9	14	14.1	mm
package height	-	0.825	0.925	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	486	-	



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2 Package outline

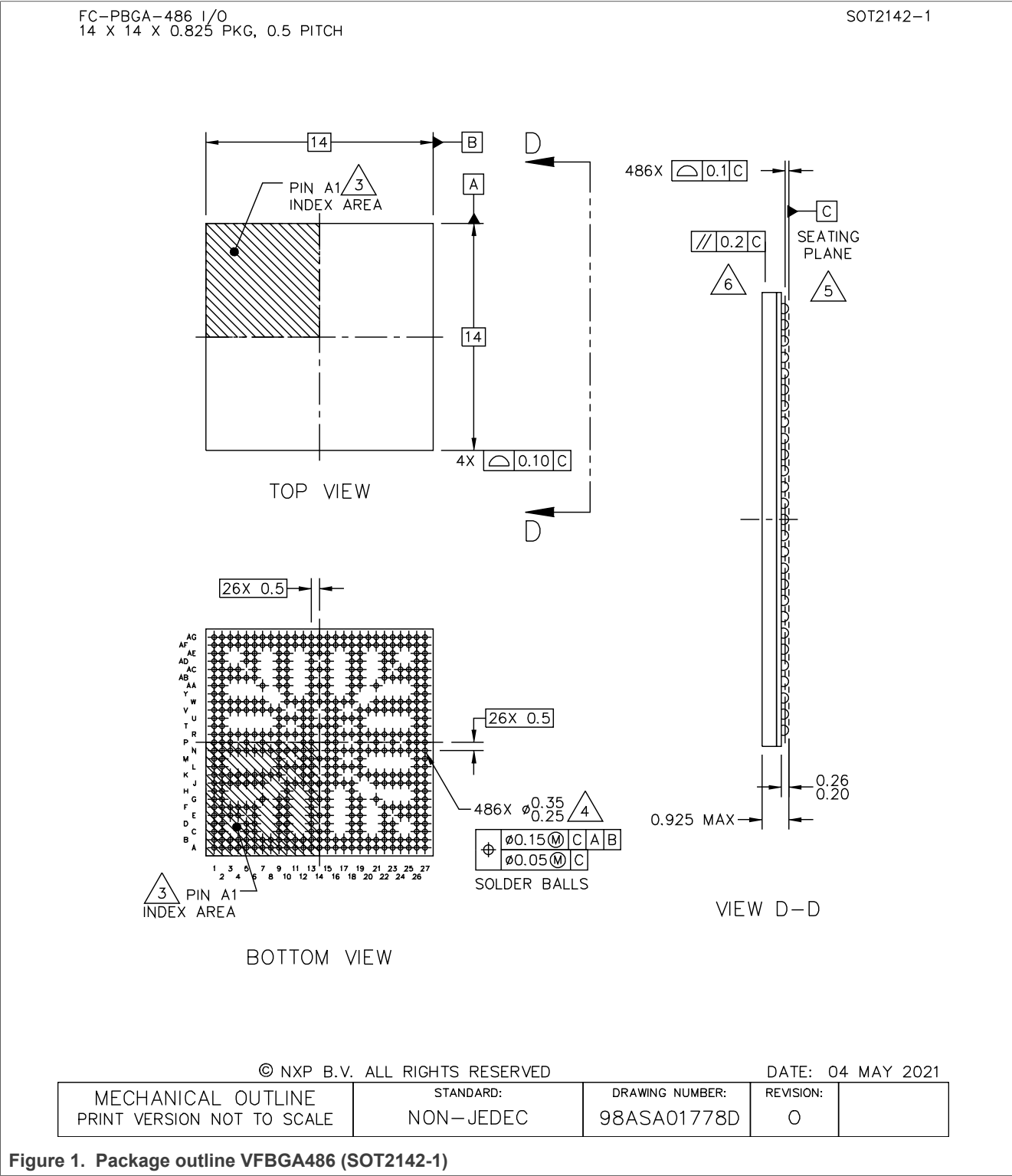
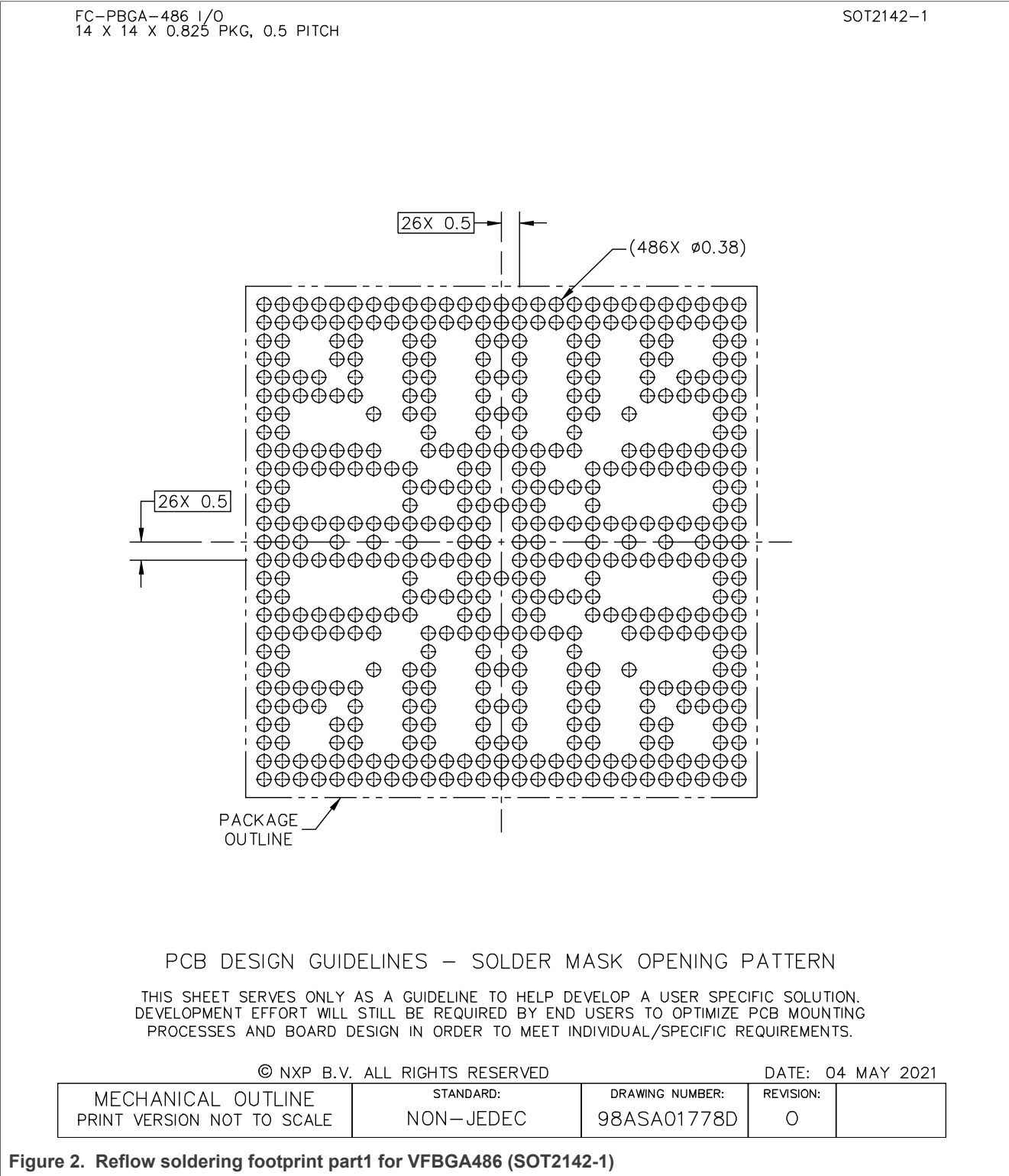


Figure 1. Package outline VFBGA486 (SOT2142-1)

VFBGA486, very thin, fine-pitch ball grid array package, 486 terminals, 0.5 mm pitch, 14 mm x 14 mm x 0.825 mm body

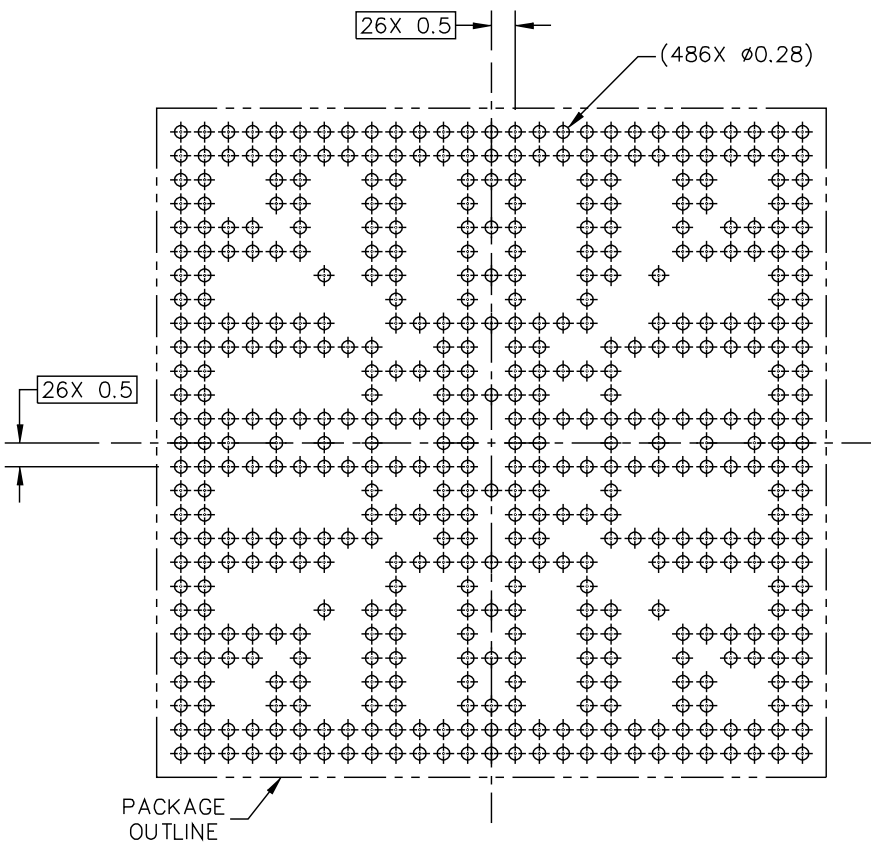
3 Soldering



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FC-PBGA-486 I/O
14 X 14 X 0.825 PKG, 0.5 PITCH

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PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

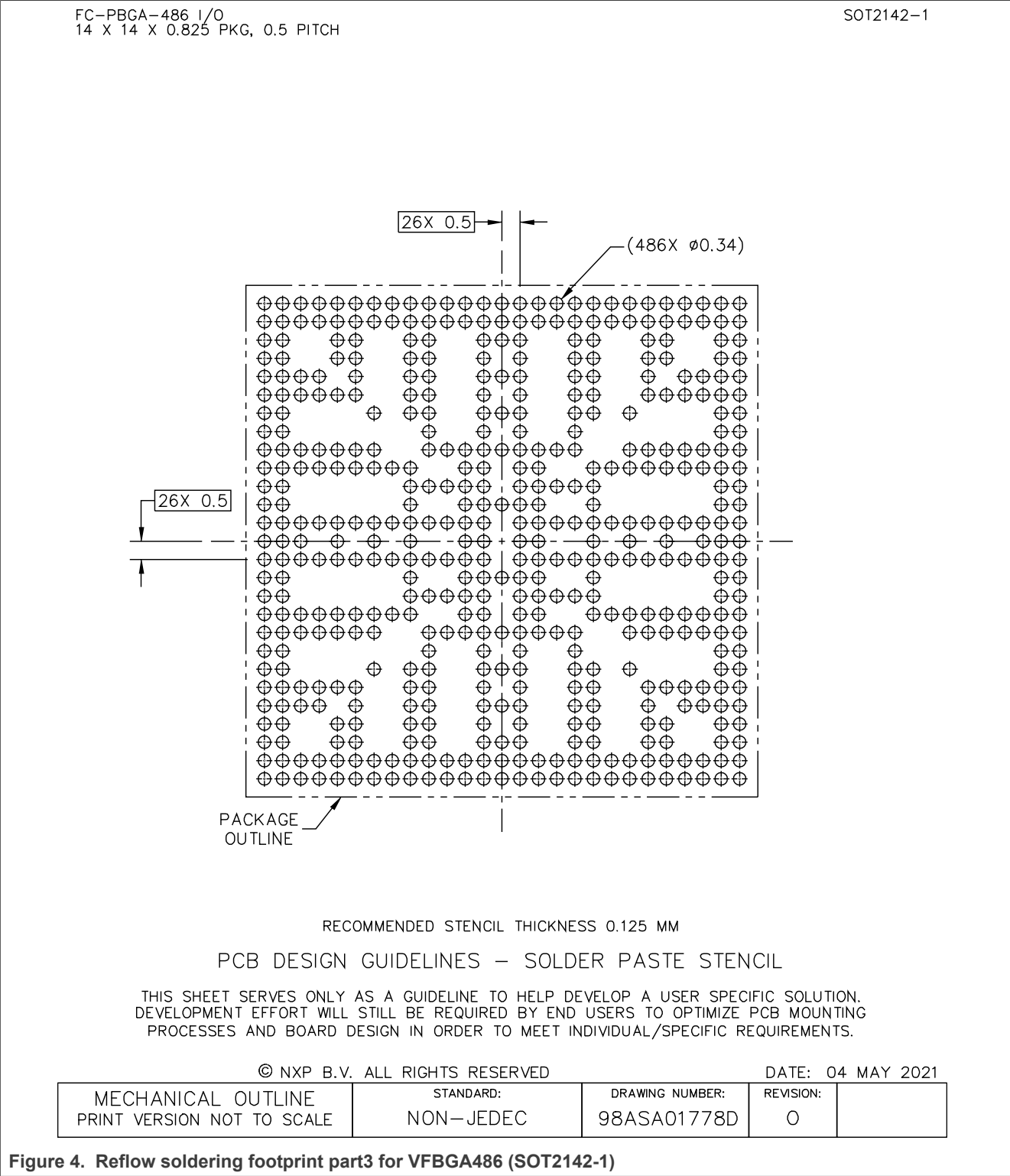
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DATE: 04 MAY 2021

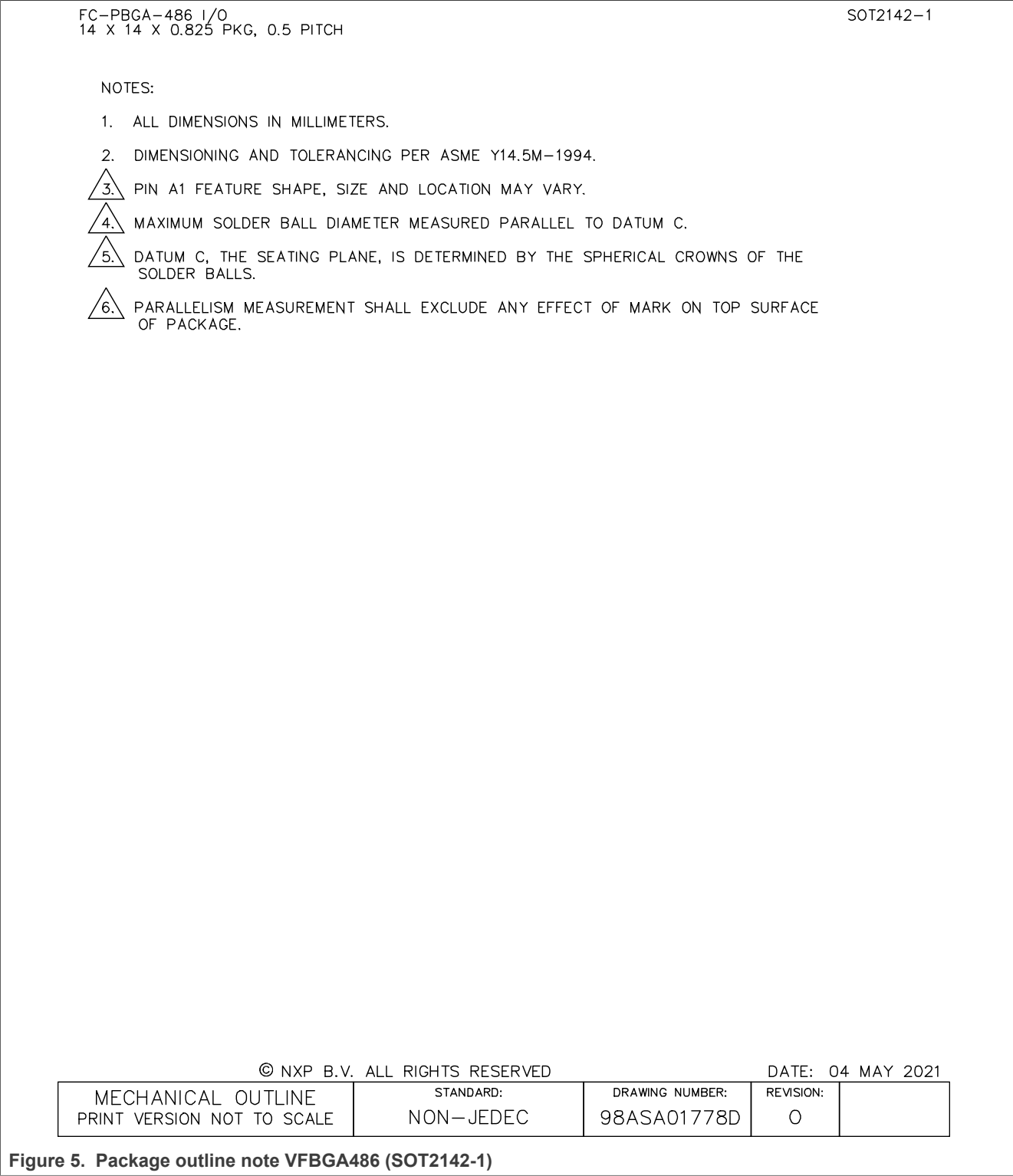
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01778D	REVISION: 0	
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Figure 3. Reflow soldering footprint part2 for VFBGA486 (SOT2142-1)

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4 Legal information

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